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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	864
Number of Logic Elements/Cells	3888
Total RAM Bits	49152
Number of I/O	260
Number of Gates	164674
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	352-LBGA Exposed Pad, Metal
Supplier Device Package	352-MBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv150-6bg352c

Revision History

Date	Version	Revision
11/98	1.0	Initial Xilinx release.
01/99-02/99	1.2-1.3	Both versions updated package drawings and specs.
05/99	1.4	Addition of package drawings and specifications.
05/99	1.5	Replaced FG 676 & FG680 package drawings.
07/99	1.6	Changed Boundary Scan Information and changed Figure 11, Boundary Scan Bit Sequence. Updated IOB Input & Output delays. Added Capacitance info for different I/O Standards. Added 5 V tolerant information. Added DLL Parameters and waveforms and new Pin-to-pin Input and Output Parameter tables for Global Clock Input to Output and Setup and Hold. Changed Configuration Information including Figures 12, 14, 17 & 19. Added device-dependent listings for quiescent currents ICCINTQ and ICCOQ. Updated IOB Input and Output Delays based on default standard of LVTTTL, 12 mA, Fast Slew Rate. Added IOB Input Switching Characteristics Standard Adjustments.
09/99	1.7	Speed grade update to preliminary status, Power-on specification and Clock-to-Out Minimums additions, "0" hold time listing explanation, quiescent current listing update, and Figure 6 ADDRA input label correction. Added T _{IJITCC} parameter, changed T _{OJIT} to T _{OPHASE} .
01/00	1.8	Update to speed.txt file 1.96. Corrections for CRs 111036, 111137, 112697, 115479, 117153, 117154, and 117612. Modified notes for Recommended Operating Conditions (voltage and temperature). Changed Bank information for V _{CCO} in CS144 package on p.43.
01/00	1.9	Updated DLL Jitter Parameter table and waveforms, added Delay Measurement Methodology table for different I/O standards, changed buffered Hex line info and Input/Output Timing measurement notes.
03/00	2.0	New TBCKO values; corrected FG680 package connection drawing; new note about status of CCLK pin after configuration.
05/00	2.1	Modified "Pins not listed..." statement. Speed grade update to Final status.
05/00	2.2	Modified Table 18.
09/00	2.3	<ul style="list-style-type: none"> Added XCV400 values to table under Minimum Clock-to-Out for Virtex Devices. Corrected Units column in table under IOB Input Switching Characteristics. Added values to table under CLB SelectRAM Switching Characteristics.
10/00	2.4	<ul style="list-style-type: none"> Corrected Pinout information for devices in the BG256, BG432, and BG560 packages in Table 18. Corrected BG256 Pin Function Diagram.
04/01	2.5	<ul style="list-style-type: none"> Revised minimums for Global Clock Set-Up and Hold for LVTTTL Standard, with DLL. Converted file to modularized format. See Virtex Data Sheet section.
03/13	4.0	The products listed in this data sheet are obsolete. See XCN10016 for further information.

Virtex Data Sheet

The Virtex Data Sheet contains the following modules:

- DS003-1, Virtex 2.5V FPGAs:
Introduction and Ordering Information (Module 1)
- DS003-2, Virtex 2.5V FPGAs:
Functional Description (Module 2)
- DS003-3, Virtex 2.5V FPGAs:
DC and Switching Characteristics (Module 3)
- DS003-4, Virtex 2.5V FPGAs:
Pinout Tables (Module 4)

Input Path

A buffer in the Virtex IOB input path routes the input signal either directly to internal logic or through an optional input flip-flop.

An optional delay element at the D-input of this flip-flop eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the FPGA, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signalling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF} . The need to supply V_{REF} imposes constraints on which standards can be used in close proximity to each other. See [I/O Banking, page 3](#).

There are optional pull-up and pull-down resistors at each user I/O input for use after configuration. Their value is in the range 50 k Ω – 100 k Ω .

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output signal can be routed to the buffer directly from the internal logic or through an optional IOB output flip-flop.

The 3-state control of the output can also be routed directly from the internal logic or through a flip-flop that provides synchronous enable and disable.

Each output driver can be individually programmed for a wide range of low-voltage signalling standards. Each output buffer can source up to 24 mA and sink up to 48mA. Drive strength and slew rate controls minimize bus transients.

In most signalling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in close proximity to each other. See [I/O Banking, page 3](#).

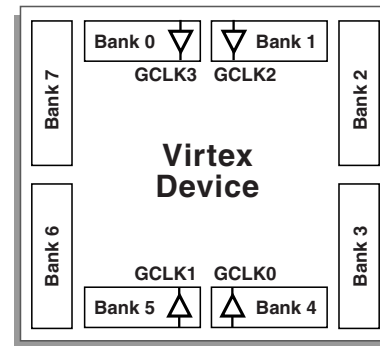
An optional weak-keeper circuit is connected to each output. When selected, the circuit monitors the voltage on the pad and weakly drives the pin High or Low to match the input signal. If the pin is connected to a multiple-source signal, the weak keeper holds the signal in its last state if all drivers are disabled. Maintaining a valid logic level in this way eliminates bus chatter.

Because the weak-keeper circuit uses the IOB input buffer to monitor the input level, an appropriate V_{REF} voltage must be provided if the signalling standard requires one. The provision of this voltage must comply with the I/O banking rules.

I/O Banking

Some of the I/O standards described above require V_{CCO} and/or V_{REF} voltages. These voltages externally and connected to device pins that serve groups of IOBs, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Eight I/O banks result from separating each edge of the FPGA into two banks, as shown in [Figure 3](#). Each bank has multiple V_{CCO} pins, all of which must be connected to the same voltage. This voltage is determined by the output standards in use.



X8778_b

Figure 3: Virtex I/O Banks

Within a bank, output standards can be mixed only if they use the same V_{CCO} . Compatible standards are shown in [Table 2](#). GTL and GTL+ appear under all voltages because their open-drain outputs do not depend on V_{CCO} .

Table 2: Compatible Output Standards

V_{CCO}	Compatible Standards
3.3 V	PCI, LVTTTL, SSTL3 I, SSTL3 II, CTT, AGP, GTL, GTL+
2.5 V	SSTL2 I, SSTL2 II, LVCMOS2, GTL, GTL+
1.5 V	HSTL I, HSTL III, HSTL IV, GTL, GTL+

Some input standards require a user-supplied threshold voltage, V_{REF} . In this case, certain user-I/O pins are automatically configured as inputs for the V_{REF} voltage. Approximately one in six of the I/O pins in the bank assume this role.

The V_{REF} pins within a bank are interconnected internally and consequently only one V_{REF} voltage can be used within each bank. All V_{REF} pins in the bank, however, must be connected to the external voltage source for correct operation.

Within a bank, inputs that require V_{REF} can be mixed with those that do not. However, only one V_{REF} voltage can be used within a bank. Input buffers that use V_{REF} are not 5 V tolerant. LVTTTL, LVCMOS2, and PCI 33 MHz 5 V, are 5 V tolerant.

The V_{CCO} and V_{REF} pins for each bank appear in the device Pinout tables and diagrams. The diagrams also show the bank affiliation of each I/O.

Within a given package, the number of V_{REF} and V_{CCO} pins can vary depending on the size of device. In larger devices,

General Purpose Routing

Most Virtex signals are routed on the general purpose routing, and consequently, the majority of interconnect resources are associated with this level of the routing hierarchy. The general routing resources are located in horizontal and vertical routing channels associated with the rows and columns CLBs. The general-purpose routing resources are listed below.

- Adjacent to each CLB is a General Routing Matrix (GRM). The GRM is the switch matrix through which horizontal and vertical routing resources connect, and is also the means by which the CLB gains access to the general purpose routing.
- 24 single-length lines route GRM signals to adjacent GRMs in each of the four directions.
- 12 buffered Hex lines route GRM signals to another GRMs six-blocks away in each one of the four directions. Organized in a staggered pattern, Hex lines can be driven only at their endpoints. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source). One third of the Hex lines are bidirectional, while the remaining ones are uni-directional.

- 12 Longlines are buffered, bidirectional wires that distribute signals across the device quickly and efficiently. Vertical Longlines span the full height of the device, and horizontal ones span the full width of the device.

I/O Routing

Virtex devices have additional routing resources around their periphery that form an interface between the CLB array and the IOBs. This additional routing, called the VersaRing, facilitates pin-swapping and pin-locking, such that logic redesigns can adapt to existing PCB layouts. Time-to-market is reduced, since PCBs and other system components can be manufactured while the logic design is still in progress.

Dedicated Routing

Some classes of signal require dedicated routing resources to maximize performance. In the Virtex architecture, dedicated routing resources are provided for two classes of signal.

- Horizontal routing resources are provided for on-chip 3-state busses. Four partitionable bus lines are provided per CLB row, permitting multiple busses within a row, as shown in [Figure 8](#).
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB.



Figure 8: BUFT Connections to Dedicated Horizontal Bus Lines

Global Routing

Global Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex devices include two tiers of global routing resources referred to as primary global and secondary local clock routing resources.

- The primary global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The primary global nets can only be driven by global buffers. There are four global buffers, one for each global net.

- The secondary local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These secondary resources are more flexible than the primary resources since they are not restricted to routing only to clock pins.

Clock Distribution

Virtex provides high-speed, low-skew clock distribution through the primary global routing resources described above. A typical clock distribution net is shown in [Figure 9](#).

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four primary global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is

selected either from these pads or from signals in the general purpose routing.



Figure 9: Global Clock Distribution Network

Delay-Locked Loop (DLL)

Associated with each global clock input buffer is a fully digital Delay-Locked Loop (DLL) that can eliminate skew between the clock input pad and internal clock-input pins throughout the device. Each DLL can drive two global clock networks. The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Clock edges reach internal flip-flops one to four clock periods after they arrive at the input. This closed-loop system effectively eliminates clock-distribution delay by ensuring that clock edges arrive at internal flip-flops in synchronism with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The DLL provides four quadrature phases of the source clock, can double the clock, or divide the clock by 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

The DLL also operates as a clock mirror. By driving the output from a DLL off-chip and then back on again, the DLL can be used to de-skew a board level clock among multiple Virtex devices.

In order to guarantee that the system clock is operating correctly prior to the FPGA starting up after configuration, the DLL can delay the completion of the configuration process until after it has achieved lock.

See **DLL Timing Parameters**, page 21 of Module 3, for frequency range information.

Boundary Scan

Virtex devices support all the mandatory boundary-scan instructions specified in the IEEE standard 1149.1. A Test Access Port (TAP) and registers are provided that implement the EXTEST, INTEST, SAMPLE/PRELOAD, BYPASS, IDCODE, USERCODE, and HIGHZ instructions. The TAP also supports two internal scan chains and configuration/readback of the device. The TAP uses dedicated package pins that always operate using LVTTTL. For TDO to operate using LVTTTL, the V_{CCO} for Bank 2 should be 3.3 V. Otherwise, TDO switches rail-to-rail between ground and V_{CCO} .

Boundary-scan operation is independent of individual IOB configurations, and unaffected by package type. All IOBs, including un-bonded ones, are treated as independent 3-state bidirectional pins in a single scan chain. Retention of the bidirectional test capability after configuration facilitates the testing of external interconnections, provided the user design or application is turned off.

Table 5 lists the boundary-scan instructions supported in Virtex FPGAs. Internal signals can be captured during EXTEST by connecting them to un-bonded or unused IOBs. They can also be connected to the unused outputs of IOBs defined as unidirectional input pins.

Before the device is configured, all instructions except USER1 and USER2 are available. After configuration, all instructions are available. During configuration, it is recommended that those operations using the boundary-scan register (SAMPLE/PRELOAD, INTEST, EXTEST) not be performed.

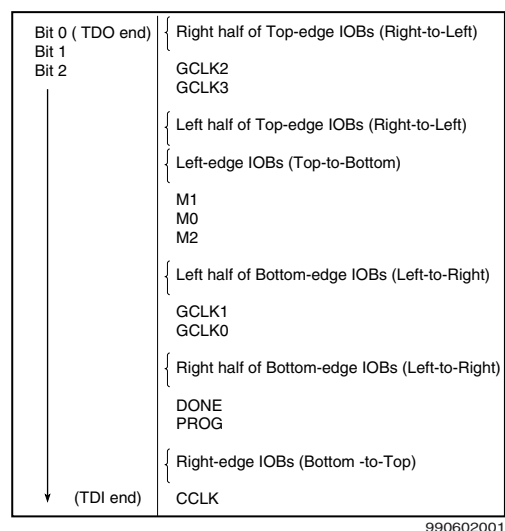


Figure 11: Boundary Scan Bit Sequence

Table 5: Boundary Scan Instructions

Boundary-Scan Command	Binary Code(4:0)	Description
EXTEST	00000	Enables boundary-scan EXTEST operation
SAMPLE/PRELOAD	00001	Enables boundary-scan SAMPLE/PRELOAD operation
USER 1	00010	Access user-defined register 1
USER 2	00011	Access user-defined register 2
CFG_OUT	00100	Access the configuration bus for read operations.
CFG_IN	00101	Access the configuration bus for write operations.
INTEST	00111	Enables boundary-scan INTEST operation
USERCODE	01000	Enables shifting out USER code
IDCODE	01001	Enables shifting out of ID Code
HIGHZ	01010	3-states output pins while enabling the Bypass Register
JSTART	01100	Clock the start-up sequence when StartupClk is TCK
BYPASS	11111	Enables BYPASS
RESERVED	All other codes	Xilinx reserved instructions

Identification Registers

The IDCODE register is supported. By using the IDCODE, the device connected to the JTAG port can be determined.

The IDCODE register has the following binary format:

vvvv:ffff:ffa:aaaa:aaaa:cccc:cccc:ccc1

where

v = the die version number

f = the family code (03h for Virtex family)

a = the number of CLB rows (ranges from 010h for XCV50 to 040h for XCV1000)

c = the company code (49h for Xilinx)

The USERCODE register is supported. By using the USERCODE, a user-programmable identification code can be loaded and shifted out for examination. The identification code is embedded in the bitstream during bitstream generation and is valid only after configuration.

Table 6: IDCODEs Assigned to Virtex FPGAs

FPGA	IDCODE
XCV50	v0610093h
XCV100	v0614093h
XCV150	v0618093h
XCV200	v061C093h
XCV300	v0620093h
XCV400	v0628093h
XCV600	v0630093h
XCV800	v0638093h
XCV1000	v0640093h

Including Boundary Scan in a Design

Since the boundary scan pins are dedicated, no special element needs to be added to the design unless an internal data register (USER1 or USER2) is desired.

If an internal data register is used, insert the boundary scan symbol and connect the necessary pins as appropriate.

Development System

Virtex FPGAs are supported by the Xilinx Foundation and Alliance CAE tools. The basic methodology for Virtex design consists of three interrelated steps: design entry, implementation, and verification. Industry-standard tools are used for design entry and simulation (for example, Synopsys FPGA Express), while Xilinx provides proprietary architecture-specific tools for implementation.

The Xilinx development system is integrated under the Xilinx Design Manager (XDM™) software, providing design-



Figure 17: SelectMAP Flowchart for Write Operation

Abort

During a given assertion of \overline{CS} , the user cannot switch from a write to a read, or vice-versa. This action causes the current packet command to be aborted. The device will remain BUSY until the aborted operation has completed. Following an abort, data is assumed to be unaligned to word boundar-

ies, and the FPGA requires a new synchronization word prior to accepting any new packets.

To initiate an abort during a write operation, de-assert \overline{WRITE} . At the rising edge of CCLK, an abort is initiated, as shown in Figure 18.



Virtex™ 2.5 V Field Programmable Gate Arrays

DS003-3 (v4.0) March 1, 2013

Production Product Specification

Virtex Electrical Characteristics

Definition of Terms

Electrical and switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications. Contact the factory for design considerations requiring more detailed information.

Table 1 correlates the current status of each Virtex device with a corresponding speed file designation.

Table 1: Virtex Device Speed Grade Designations

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XCV50			–6, –5, –4
XCV100			–6, –5, –4
XCV150			–6, –5, –4
XCV200			–6, –5, –4
XCV300			–6, –5, –4
XCV400			–6, –5, –4
XCV600			–6, –5, –4
XCV800			–6, –5, –4
XCV1000			–6, –5, –4

All specifications are subject to change without notice.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device⁽¹⁾ from 0 V. The current is highest at the fastest suggested ramp rate (0 V to nominal voltage in 2 ms) and is lowest at the slowest allowed ramp rate (0 V to nominal voltage in 50 ms). For more details on power supply requirements, see Application Note XAPP158 on www.xilinx.com.

Product	Description ⁽²⁾	Current Requirement ^(1,3)
Virtex Family, Commercial Grade	Minimum required current supply	500 mA
Virtex Family, Industrial Grade	Minimum required current supply	2 A

Notes:

1. Ramp rate used for this specification is from 0 - 2.7 VDC. Peak current occurs on or near the internal power-on reset threshold of 1.0V and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents can result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed output currents over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} for each standard with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, min	V, max	V, min	V, max	V, Max	V, Min	mA	mA
LVTTL ⁽¹⁾	-0.5	0.8	2.0	5.5	0.4	2.4	24	-24
LVC MOS2	-0.5	.7	1.7	5.5	0.4	1.9	12	-12
PCI, 3.3 V	-0.5	44% V_{CCINT}	60% V_{CCINT}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
PCI, 5.0 V	-0.5	0.8	2.0	5.5	0.55	2.4	Note 2	Note 2
GTL	-0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	n/a	40	n/a
GTL+	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	n/a	36	n/a
HSTL I ⁽³⁾	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	8	-8
HSTL III	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	24	-8
HSTL IV	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	48	-8
SSTL3 I	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.6$	$V_{REF} + 0.6$	8	-8
SSTL3 II	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.8$	$V_{REF} + 0.8$	16	-16
SSTL2 I	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.61$	$V_{REF} + 0.61$	7.6	-7.6
SSTL2 II	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.80$	$V_{REF} + 0.80$	15.2	-15.2
CTT	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.4$	$V_{REF} + 0.4$	8	-8
AGP	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:

1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on www.xilinx.com.

Description	Device	Symbol	Speed Grade				Units
			Min	-6	-5	-4	
Setup and Hold Times with respect to Clock CLK at IOB input register ⁽¹⁾			Setup Time / Hold Time				
Pad, no delay	All	T _{IO PICK} /T _{IO ICKP}	0.8 / 0	1.6 / 0	1.8 / 0	2.0 / 0	ns, min
Pad, with delay	XCV50	T _{IO PICKD} /T _{IO ICKPD}	1.9 / 0	3.7 / 0	4.1 / 0	4.7 / 0	ns, min
	XCV100		1.9 / 0	3.7 / 0	4.1 / 0	4.7 / 0	ns, min
	XCV150		1.9 / 0	3.8 / 0	4.3 / 0	4.9 / 0	ns, min
	XCV200		2.0 / 0	3.9 / 0	4.4 / 0	5.0 / 0	ns, min
	XCV300		2.0 / 0	3.9 / 0	4.4 / 0	5.0 / 0	ns, min
	XCV400		2.1 / 0	4.1 / 0	4.6 / 0	5.3 / 0	ns, min
	XCV600		2.1 / 0	4.2 / 0	4.7 / 0	5.4 / 0	ns, min
	XCV800		2.2 / 0	4.4 / 0	4.9 / 0	5.6 / 0	ns, min
	XCV1000		2.3 / 0	4.5 / 0	5.0 / 0	5.8 / 0	ns, min
ICE input	All	T _{IO ICECK} /T _{IO CKICE}	0.37/ 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, max
Set/Reset Delays							
SR input (IFF, synchronous)	All	T _{IO SRCKI}	0.49	1.0	1.1	1.3	ns, max
SR input to IQ (asynchronous)	All	T _{IO SRIQ}	0.70	1.4	1.6	1.8	ns, max
GSR to output IQ	All	T _{GSRQ}	4.9	9.7	10.9	12.5	ns, max

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. Input timing for LVTTTL is measured at 1.4 V. For other I/O standards, see [Table 3](#).

Calculation of $T_{i\text{oop}}$ as a Function of Capacitance

$T_{i\text{oop}}$ is the propagation delay from the O Input of the IOB to the pad. The values for $T_{i\text{oop}}$ were based on the standard capacitive load (C_{sl}) for each I/O standard as listed in [Table 2](#).

Table 2: Constants for Calculating $T_{i\text{oop}}$

Standard	Csl (pF)	fl (ns/pF)
LVTTL Fast Slew Rate, 2mA drive	35	0.41
LVTTL Fast Slew Rate, 4mA drive	35	0.20
LVTTL Fast Slew Rate, 6mA drive	35	0.13
LVTTL Fast Slew Rate, 8mA drive	35	0.079
LVTTL Fast Slew Rate, 12mA drive	35	0.044
LVTTL Fast Slew Rate, 16mA drive	35	0.043
LVTTL Fast Slew Rate, 24mA drive	35	0.033
LVTTL Slow Slew Rate, 2mA drive	35	0.41
LVTTL Slow Slew Rate, 4mA drive	35	0.20
LVTTL Slow Slew Rate, 6mA drive	35	0.100
LVTTL Slow Slew Rate, 8mA drive	35	0.086
LVTTL Slow Slew Rate, 12mA drive	35	0.058
LVTTL Slow Slew Rate, 16mA drive	35	0.050
LVTTL Slow Slew Rate, 24mA drive	35	0.048
LVCMS2	35	0.041
PCI 33MHz 5V	50	0.050
PCI 33MHZ 3.3 V	10	0.050
PCI 66 MHz 3.3 V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:

1. I/O parameter measurements are made with the capacitance values shown above. See Application Note XAPP133 on www.xilinx.com for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

For other capacitive loads, use the formulas below to calculate the corresponding $T_{i\text{oop}}$.

$$T_{i\text{oop}} = T_{i\text{oop}} + T_{\text{opadjust}} + (C_{\text{load}} - C_{sl}) * fl$$

Where:

T_{opadjust} is reported above in the Output Delay Adjustment section.

C_{load} is the capacitive load for the design.

Table 3: Delay Measurement Methodology

Standard	V_L (1)	V_H (1)	Meas. Point	V_{REF} Typ (2)
LVTTL	0	3	1.4	-
LVCMS2	0	2.5	1.125	-
PCI33_5	Per PCI Spec			-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.80
GTL+	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.0
HSTL Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL Class III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL Class IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
SSTL3 I & II	$V_{REF} - 1.0$	$V_{REF} + 1.0$	V_{REF}	1.5
SSTL2 I & II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
CTT	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.5
AGP	$V_{REF} - (0.2 \times V_{CCO})$	$V_{REF} + (0.2 \times V_{CCO})$	V_{REF}	Per AGP Spec

Notes:

1. Input waveform switches between V_L and V_H .
2. Measurements are made at V_{REF} (Typ), Maximum, and Minimum. Worst-case values are reported.
3. I/O parameter measurements are made with the capacitance values shown in [Table 2](#). See Application Note XAPP133 on www.xilinx.com for appropriate terminations.
4. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Clock Distribution Guidelines

Description	Device	Symbol	Speed Grade			Units
			-6	-5	-4	
Global Clock Skew ⁽¹⁾						
Global Clock Skew between IOB Flip-flops	XCV50	T _{GSKEWIOB}	0.10	0.12	0.14	ns, max
	XCV100		0.12	0.13	0.15	ns, max
	XCV150		0.12	0.13	0.15	ns, max
	XCV200		0.13	0.14	0.16	ns, max
	XCV300		0.14	0.16	0.18	ns, max
	XCV400		0.13	0.13	0.14	ns, max
	XCV600		0.14	0.15	0.17	ns, max
	XCV800		0.16	0.17	0.20	ns, max
	XCV1000		0.20	0.23	0.25	ns, max

Notes:

- These clock-skew delays are provided for guidance only. They reflect the delays encountered in a typical design under worst-case conditions. Precise values for a particular design are provided by the timing analyzer.

Clock Distribution Switching Characteristics

Description	Symbol	Speed Grade				Units
		Min	-6	-5	-4	
GCLK IOB and Buffer						
Global Clock PAD to output.	T _{GPIO}	0.33	0.7	0.8	0.9	ns, max
Global Clock Buffer I input to O output	T _{GIO}	0.34	0.7	0.8	0.9	ns, max

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used. The values listed below are worst-case. Precise values are provided by the timing analyzer.

Description	Symbol	Speed Grade				Units
		Min	-6	-5	-4	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.29	0.6	0.7	0.8	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.32	0.7	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.36	0.8	0.8	1.0	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.44	0.9	1.0	1.2	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.17	0.32	0.36	0.42	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.31	0.7	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.27	0.53	0.6	0.7	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.54	1.1	1.2	1.4	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.6	1.2	1.4	1.6	ns, max
Setup and Hold Times before/after Clock CLK ⁽¹⁾	Setup Time / Hold Time					
4-input function: F/G Inputs	T _{ICK} /T _{CKI}	0.6 / 0	1.2 / 0	1.4 / 0	1.5 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} /T _{CKIF5}	0.7 / 0	1.3 / 0	1.5 / 0	1.7 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} /T _{CKF5IN}	0.46 / 0	1.0 / 0	1.1 / 0	1.2 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} /T _{CKIF6}	0.8 / 0	1.5 / 0	1.7 / 0	1.9 / 0	ns, min
BX/BY inputs	T _{DICK} /T _{CKDI}	0.30 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} /T _{CKCE}	0.37 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} T _{CKR}	0.33 / 0	0.7 / 0	0.8 / 0	0.9 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.8	1.5	1.7	2.0	ns, min
Minimum Pulse Width, Low	T _{CL}	0.8	1.5	1.7	2.0	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	1.3	2.5	2.8	3.3	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.54	1.1	1.3	1.4	ns, max
Delay from GSR to XQ/YQ outputs	T _{IOGSRQ}	4.9	9.7	10.9	12.5	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG} (MHz)	625	333	294	250	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Virtex Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted

Global Clock Set-Up and Hold for LVTTL Standard, *with DLL*

Description	Symbol	Device	Speed Grade				Units
			Min	-6	-5	-4	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in Input Delay Adjustments.							
No Delay Global Clock and IFF, with DLL	T_{PSDLL}/T_{PHDLL}	XCV50	0.40 / -0.4	1.7 / -0.4	1.8 / -0.4	2.1 / -0.4	ns, min
		XCV100	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV150	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV200	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV300	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV400	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV600	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV800	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min
		XCV1000	0.40 / -0.4	1.7 / -0.4	1.9 / -0.4	2.1 / -0.4	ns, min

IFF = Input Flip-Flop or Latch

Notes:

1. Set-up time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
2. DLL output jitter is already included in the timing calculation.
3. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 3: Virtex Pinout Tables (BGA)

Pin Name	Device	BG256	BG352	BG432	BG560
GCK0	All	Y11	AE13	AL16	AL17
GCK1	All	Y10	AF14	AK16	AJ17
GCK2	All	A10	B14	A16	D17
GCK3	All	B10	D14	D17	A17
M0	All	Y1	AD24	AH28	AJ29
M1	All	U3	AB23	AH29	AK30
M2	All	W2	AC23	AJ28	AN32
CCLK	All	B19	C3	D4	C4
PROGRAM	All	Y20	AC4	AH3	AM1
DONE	All	W19	AD3	AH4	AJ5
INIT	All	U18	AD2	AJ2	AH5
BUSY/DOUT	All	D18	E4	D3	D4
D0/DIN	All	C19	D3	C2	E4
D1	All	E20	G1	K4	K3
D2	All	G19	J3	K2	L4
D3	All	J19	M3	P4	P3
D4	All	M19	R3	V4	W4
D5	All	P19	U4	AB1	AB5
D6	All	T20	V3	AB3	AC4
D7	All	V19	AC3	AG4	AJ4
WRITE	All	A19	D5	B4	D6
CS	All	B18	C4	D5	A2
TDI	All	C17	B3	B3	D5
TDO	All	A20	D4	C4	E6
TMS	All	D3	D23	D29	B33
TCK	All	A1	C24	D28	E29
DXN	All	W3	AD23	AH27	AK29
DXP	All	V4	AE24	AK29	AJ28

Table 3: Virtex Pinout Tables (BGA) (Continued)

Pin Name	Device	BG256	BG352	BG432	BG560
V_{CCINT} Notes: <ul style="list-style-type: none"> Superset includes all pins, including the ones in bold type. Subset excludes pins in bold type. In BG352, for XCV300 all the V_{CCINT} pins in the superset must be connected. For XCV150/200, V_{CCINT} pins in the subset must be connected, and pins in bold type can be left unconnected (these unconnected pins cannot be used as user I/O.) In BG432, for XCV400/600/800 all V_{CCINT} pins in the superset must be connected. For XCV300, V_{CCINT} pins in the subset must be connected, and pins in bold type can be left unconnected (these unconnected pins cannot be used as user I/O.) In BG560, for XCV800/1000 all V_{CCINT} pins in the superset must be connected. For XCV400/600, V_{CCINT} pins in the subset must be connected, and pins in bold type can be left unconnected (these unconnected pins cannot be used as user I/O.) 	XCV50/100	C10, D6, D15, F4, F17, L3, L18, R4, R17, U6, U15, V10	N/A	N/A	N/A
	XCV150/200/300	Same as above	A20, C14, D10, J24, K4, P2, P25, V24, W2, AC10, AE14, AE19, B16, D12, L1, L25, R23, T1, AF11, AF16	A10, A17, B23, C14, C19, K3, K29, N2, N29, T1, T29, W2, W31, AB2, AB30, AJ10, AJ16, AK13, AK19, AK22, B26, C7, F1, F30, AE29, AF1, AH8, AH24	N/A
	XCV400/600/800/1000	N/A	N/A	Same as above	A21, B14, B18, B28, C24, E9, E12, F2, H30, J1, K32, N1, N33, U5, U30, Y2, Y31, AD2, AD32, AG3, AG31, AK8, AK11, AK17, AK20, AL14, AL27, AN25, B12, C22, M3, N29, AB2, AB32, AJ13, AL22
V _{CCO} , Bank 0	All	D7, D8	A17, B25, D19	A21, C29, D21	A22, A26, A30, B19, B32
V _{CCO} , Bank 1	All	D13, D14	A10, D7, D13	A1, A11, D11	A10, A16, B13, C3, E5
V _{CCO} , Bank 2	All	G17, H17	B2, H4, K1	C3, L1, L4	B2, D1, H1, M1, R2
V _{CCO} , Bank 3	All	N17, P17	P4, U1, Y4	AA1, AA4, AJ3	V1, AA2, AD1, AK1, AL2
V _{CCO} , Bank 4	All	U13, U14	AC8, AE2, AF10	AH11, AL1, AL11	AM2, AM15, AN4, AN8, AN12
V _{CCO} , Bank 5	All	U7, U8	AC14, AC20, AF17	AH21, AJ29, AL21	AL31, AM21, AN18, AN24, AN30
V _{CCO} , Bank 6	All	N4, P4	U26, W23, AE25	AA28, AA31, AL31	W32, AB33, AF33, AK33, AM32

Table 3: Virtex Pinout Tables (BGA) (Continued)

Pin Name	Device	BG256	BG352	BG432	BG560
V_{REF} Bank 7 (V _{REF} pins are listed incrementally. Connect all pins listed for both the required device and all smaller devices listed in the same package.) Within each bank, if input reference voltage is not required, all V _{REF} pins are general I/O.	XCV50	G3, H1	N/A	N/A	N/A
	XCV100/150	... + D1	D26, G26, L26	N/A	N/A
	XCV200/300	... + B2	... + E24	F28, F31, J30, N30	N/A
	XCV400	N/A	N/A	... + R31	E31, G31, K31, P31, T31
	XCV600	N/A	N/A	... + J28	... + H32
	XCV800	N/A	N/A	... + M28	... + L33
	XCV1000	N/A	N/A	N/A	... + D31
GND	All	C3, C18, D4, D5, D9, D10, D11, D12, D16, D17, E4, E17, J4, J17, K4, K17, L4, L17, M4, M17, T4, T17, U4, U5, U9, U10, U11, U12, U16, U17, V3, V18	A1, A2, A5, A8, A14, A19, A22, A25, A26, B1, B26, E1, E26, H1, H26, N1, P26, W1, W26, AB1, AB26, AE1, AE26, AF1, AF2, AF5, AF8, AF13, AF19, AF22, AF25, AF26	A2, A3, A7, A9, A14, A18, A23, A25, A29, A30, B1, B2, B30, B31, C1, C31, D16, G1, G31, J1, J31, P1, P31, T4, T28, V1, V31, AC1, AC31, AE1, AE31, AH16, AJ1, AJ31, AK1, AK2, AK30, AK31, AL2, AL3, AL7, AL9, AL14, AL18, AL23, AL25, AL29, AL30	A1, A7, A12, A14, A18, A20, A24, A29, A32, A33, B1, B6, B9, B15, B23, B27, B31, C2, E1, F32, G2, G33, J32, K1, L2, M33, P1, P33, R32, T1, V33, W2, Y1, Y33, AB1, AC32, AD33, AE2, AG1, AG32, AH2, AJ33, AL32, AM3, AM7, AM11, AM19, AM25, AM28, AM33, AN1, AN2, AN5, AN10, AN14, AN16, AN20, AN22, AN27, AN33
GND ⁽¹⁾	All	J9, J10, J11, J12, K9, K10, K11, K12, L9, L10, L11, L12, M9, M10, M11, M12	N/A	N/A	N/A
No Connect	All	N/A	N/A	N/A	C31, AC2, AK4, AL3

Notes:

1. 16 extra balls (grounded) at package center.

BG352 Pin Function Diagram

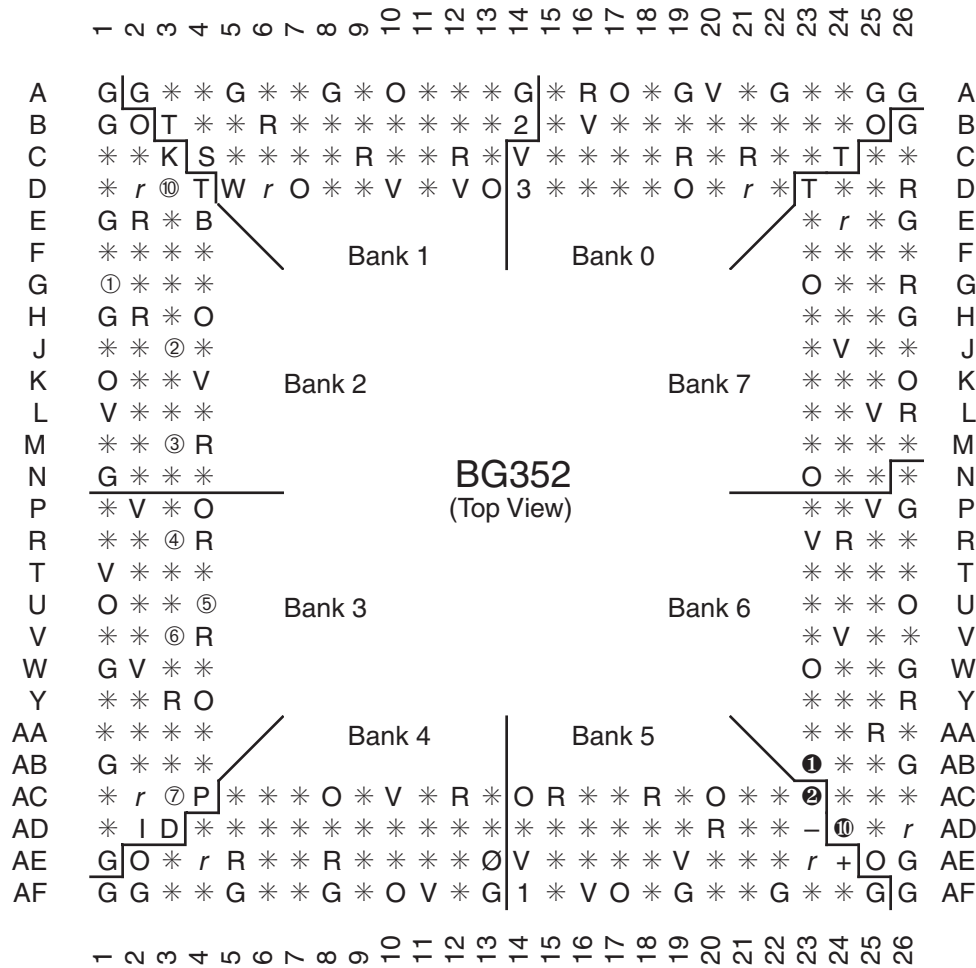
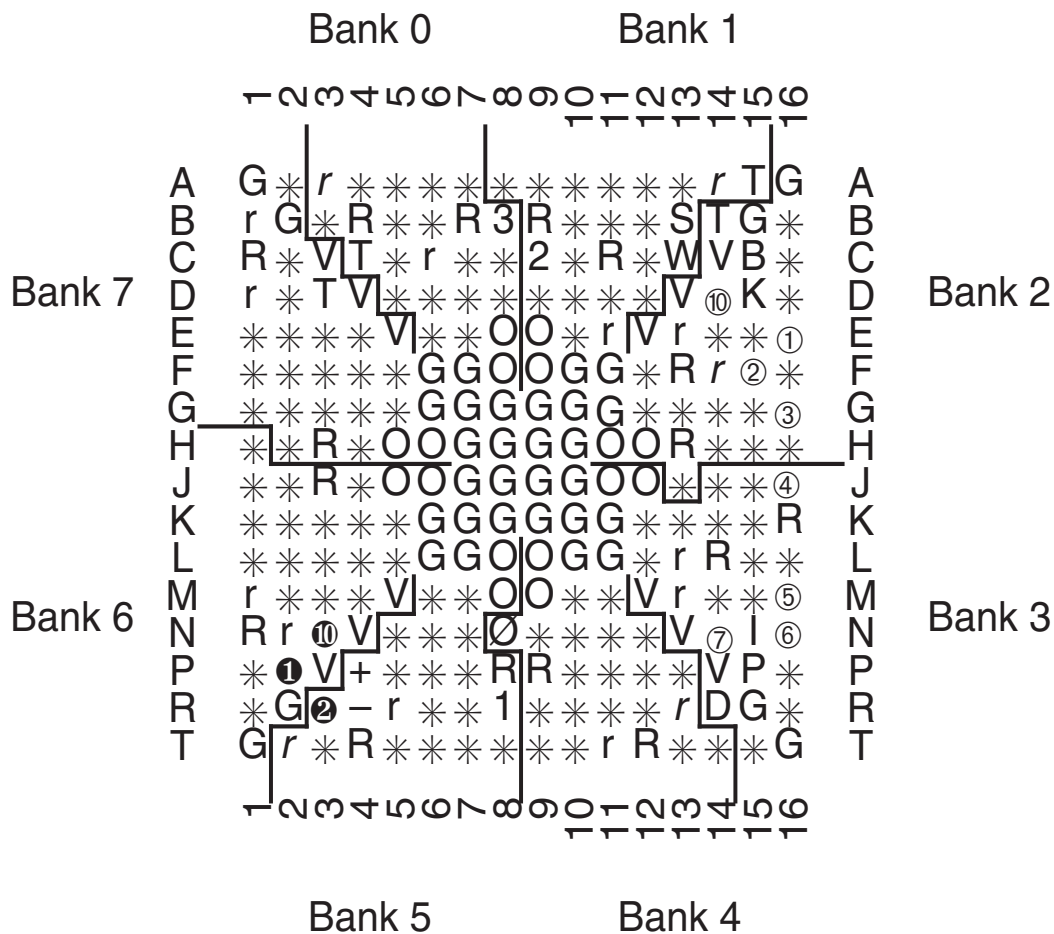


Figure 5: BG352 Pin Function Diagram

FG256 Pin Function Diagram



FG256
(Top view)

Figure 8: FG256 Pin Function Diagram